

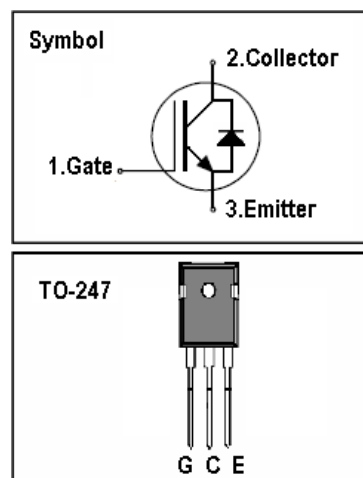
## IGBT

### Features

- 1200V, 25A,  $V_{CE(sat)(typ.)}=2.3\text{ V}@V_{GE}=15\text{V}$
- High speed switching
- Higher system efficiency
- Soft current turn-off waveforms
- Square RBSOA

### General Description

DAXIN's IGBTs offer lower losses and higher energy for application such as motor drive, UPS, inverter and other soft switching applications.



### Absolute Maximum Ratings

Symbol	Parameter	Value	Units
$V_{CES}$	Collector-Emitter Voltage	1200	V
$V_{GES}$	Gate-Emitter Voltage	$\pm 30$	V
$I_C$	Continuous Collector Current ( $T_C=25\text{ }^\circ\text{C}$ )	50	A
	Continuous Collector Current ( $T_C=100\text{ }^\circ\text{C}$ )	25	A
$I_{CM}$	Pulsed Collector Current (Note 1)	100	A
$I_F$	Diode Continuous Forward Current ( $T_C=100\text{ }^\circ\text{C}$ )	25	A
$I_{FM}$	Diode Maximum Forward Current (Note 1)	100	A
$t_{sc}$	Short Circuit Withstand Time	10	us
$t_{sc(Max)}$	Maximum Short Circuit Withstand Time	>23	us
$I_{sc}$	Short Circuit Current	140	A
$P_D$	Maximum Power Dissipation ( $T_C=25\text{ }^\circ\text{C}$ )	255	W
	Maximum Power Dissipation ( $T_C=100\text{ }^\circ\text{C}$ )	102	W
$T_J$	Operating Junction Temperature Range	-55 to +150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to +150	$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	Max.	Units
$R_{thj-c}$	Thermal Resistance, Junction to case for IGBT	0.49	$^\circ\text{C}/\text{W}$
$R_{thj-c}$	Thermal Resistance, Junction to case for Diode	1.31	$^\circ\text{C}/\text{W}$
$R_{thj-a}$	Thermal Resistance, Junction to Ambient	40	$^\circ\text{C}/\text{W}$

**Electrical Characteristics** ( $T_C=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$BV_{CES}$	Collector-Emitter Breakdown Voltage	$V_{GE}=0V, I_C=250\mu A$	1200	-	-	V
$I_{CES}$	Collector-Emitter Leakage Current	$V_{CE}=1200V, V_{GE}=0V$	-	-	250	$\mu A$
$I_{GES}$	Gate Leakage Current, Forward	$V_{GE}=30V, V_{CE}=0V$	-	-	100	nA
	Gate Leakage Current, Reverse	$V_{GE}=-30V, V_{CE}=0V$	-	-	-100	nA
$V_{GE(th)}$	Gate Threshold Voltage	$V_{GE}=V_{CE}, I_C=250\mu A$	4.5	5.0	5.5	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$V_{GE}=15V, I_C=25A$	-	2.3	2.6	V
$Q_g$	Total Gate Charge	$V_{CC}=960V$ $V_{GE}=15V$ $I_C=25A$	-	141		nC
$Q_{ge}$	Gate-Emitter Charge		-	14		nC
$Q_{gc}$	Gate-Collector Charge		-	90		nC
$t_{d(on)}$	Turn-on Delay Time	$V_{CC}=600V$ $V_{GE}=15V$ $I_C=25A$ $R_G=10\Omega$ Inductive Load $T_C=25^\circ\text{C}$	-	20	-	ns
$t_r$	Turn-on Rise Time		-	43	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	270	-	ns
$t_f$	Turn-off Fall Time		-	168	-	ns
$E_{on}$	Turn-on Switching Loss		-	1.35	-	mJ
$E_{off}$	Turn-off Switching Loss		-	2.05	-	mJ
$E_{ts}$	Total Switching Loss		-	3.40	-	mJ
$C_{ies}$	Input Capacitance	$V_{CE}=25V$ $V_{GE}=0V$ $f=1\text{MHz}$	-	1080	-	pF
$C_{oes}$	Output Capacitance		-	175	-	pF
$C_{res}$	Reverse Transfer Capacitance		-	120	-	pF
$R_{Gint}$	Integrated gate resistor	$f=1\text{M}; V_{pp}=1V$		8.0		$\Omega$

**Electrical Characteristics of Diode** ( $T_C=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_F$	Diode Forward Voltage	$I_F=25A$	-	2.1	2.5	V
$t_{rr}$	Diode Reverse Recovery Time	$V_{CE}=600V$ $I_F=25A$ $dI_F/dt=500A/\mu s$	-	100	120	ns
$I_{rr}$	Diode peak Reverse Recovery Current		-	17	20	A
$Q_{rr}$	Diode Reverse Recovery Charge		-	1100	1300	nC

**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature

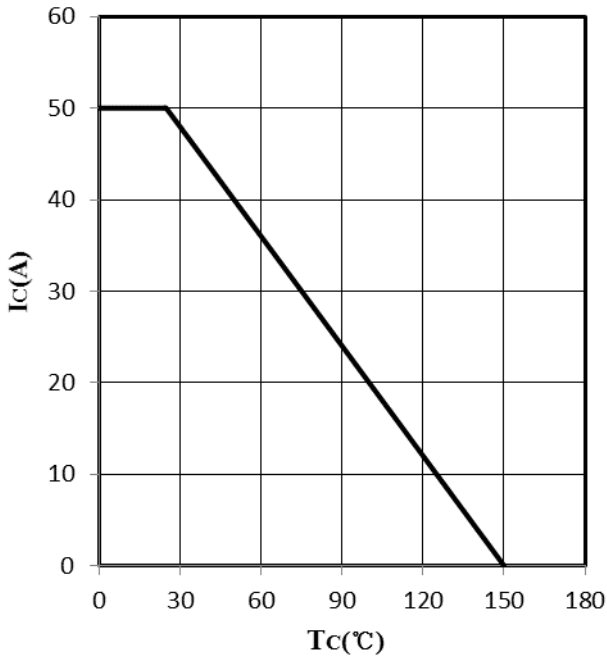


Fig 1. DC Collector current as a function of case temperature ( $V_{GE} \geq 15V$ ,  $T_j \leq 150^\circ C$ )

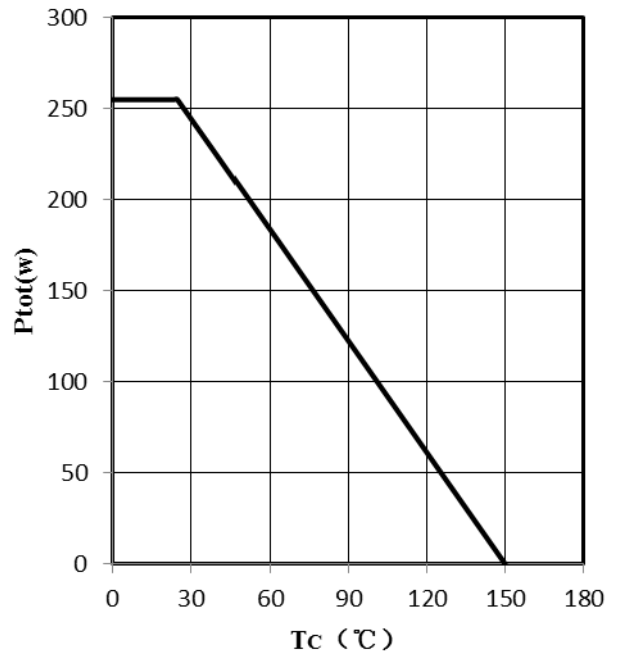


Fig 2. Power dissipation as a function of case temperature ( $T_j \leq 150^\circ C$ )

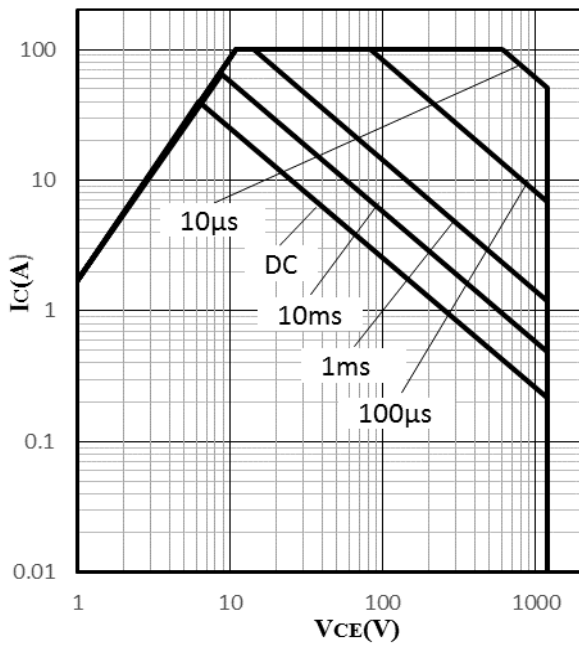


Fig 3. IGBT Forward safe operation area

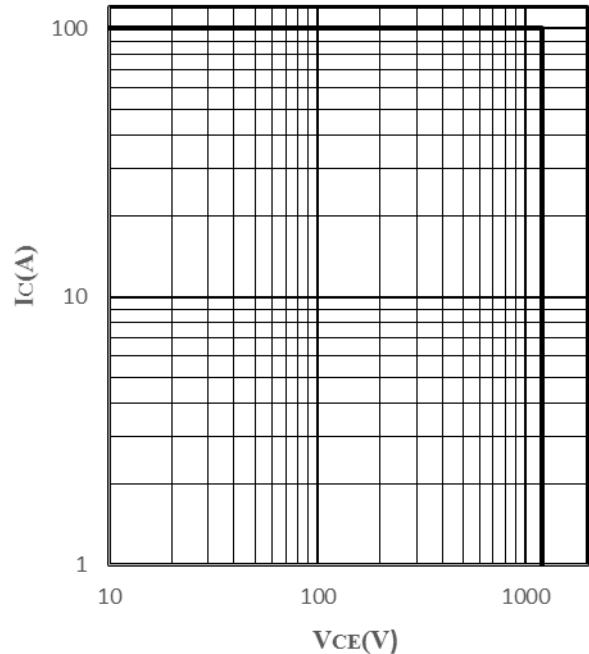


Fig 4. IGBT Reverse safe operation area

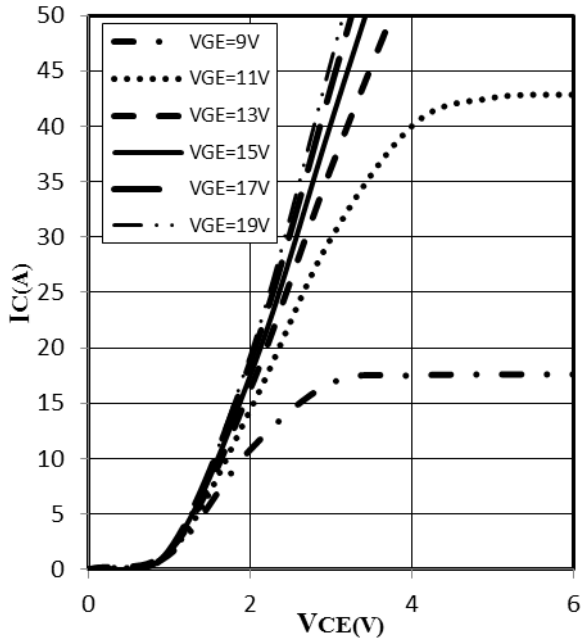


Fig 5. Typical output characteristic (Tj=25°C)

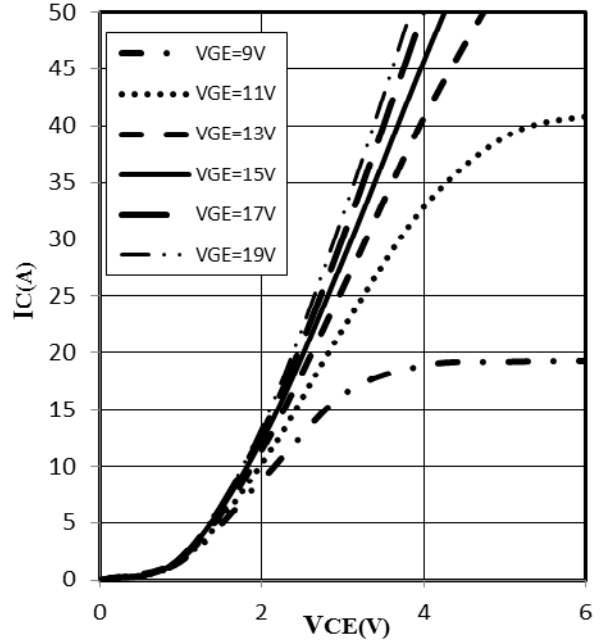


Fig 6. Typical output characteristic (Tj=125°C)

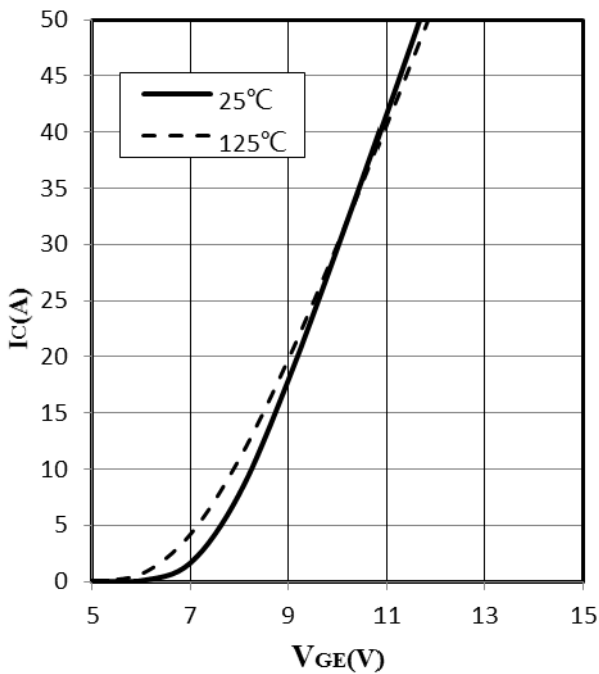


Fig 7. Typical transfer characteristic (VCE=20V)

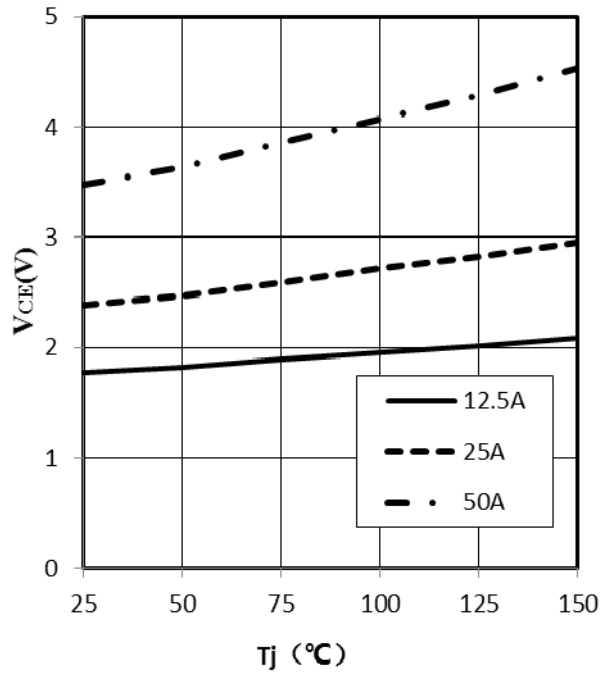


Fig 8. Typical collector-emitter saturation voltage as a function of junction temperature (VGE=15V)

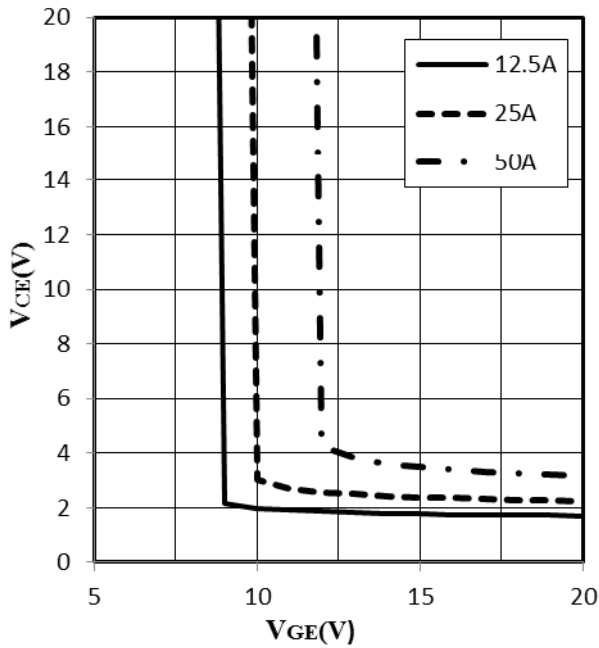


Fig 9. Typical collector-emitter saturation voltage as a function of  $V_{GE}$  ( $T_j=25^\circ\text{C}$ )

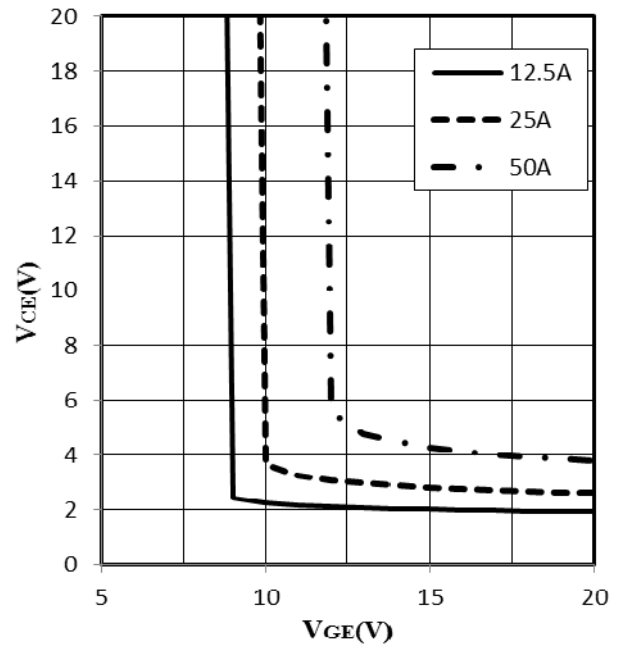


Fig 10. Typical collector-emitter saturation voltage as a function of  $V_{GE}$  ( $T_j=125^\circ\text{C}$ )

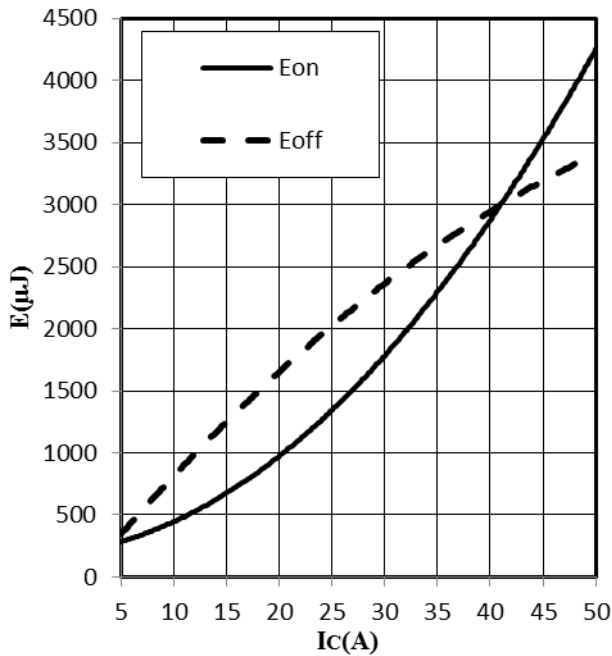


Fig 11. Typical switch energy as a function of  $I_c$  (inductive load,  $T_j=25^\circ\text{C}$ ,  $V_{CE}=600\text{V}$ ,  $V_{GE}=15\text{V}$ ,  $R_G=10\Omega$ )

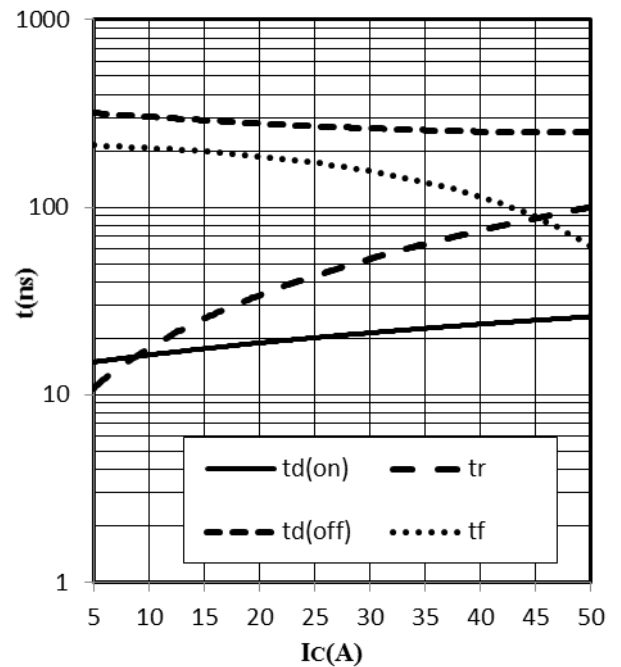


Fig 12. Typical switch time as a function of  $I_c$  (inductive load,  $T_j=25^\circ\text{C}$ ,  $V_{CE}=600\text{V}$ ,  $V_{GE}=15\text{V}$ ,  $R_G=10\Omega$ )

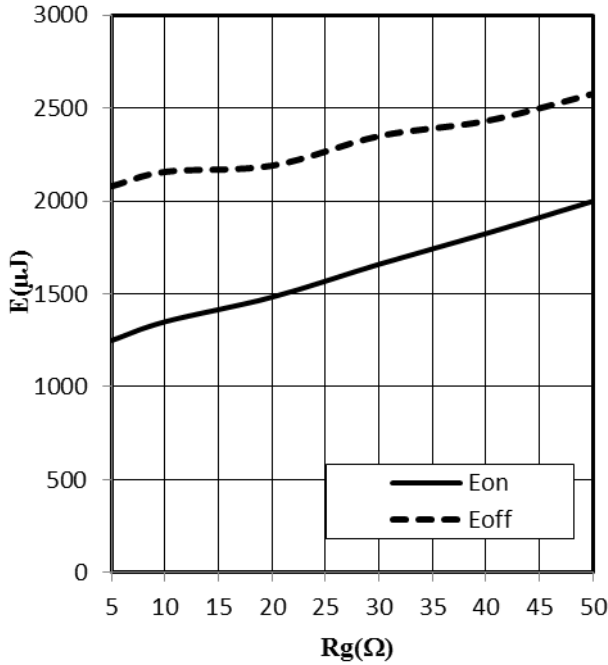


Fig 13. Typical switch energy as a function of  $R_G$   
 (inductive load,  $T_J=25^\circ\text{C}$ ,  $V_{CE}=600\text{V}$ ,  $V_{GE}=15\text{V}$ ,  $I_C=25\text{A}$ )

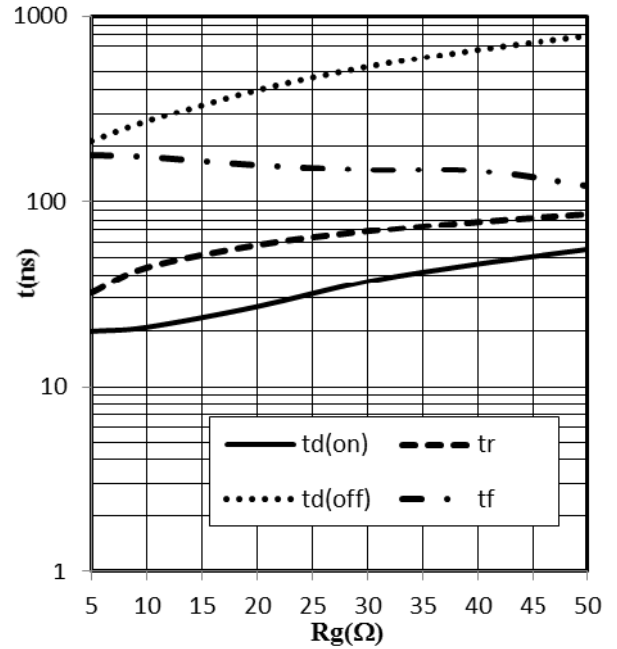


Fig 14. Typical switch time as a function of  $R_G$   
 (inductive load,  $T_J=25^\circ\text{C}$ ,  $V_{CE}=600\text{V}$ ,  $V_{GE}=15\text{V}$ ,  $I_C=25\text{A}$ )

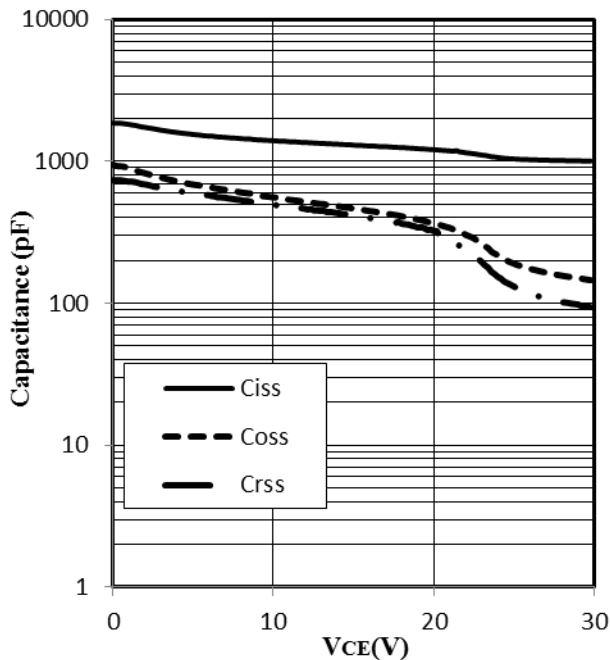


Fig 15. Typical capacitance as a function of collector-emitter voltage ( $V_{GE}=0\text{V}$ ,  $f=1\text{MHz}$ )

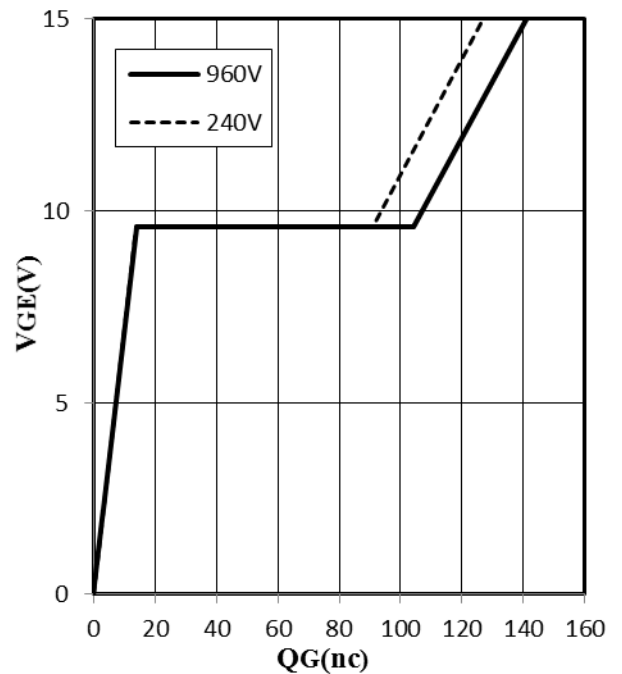


Fig 16. Typical gate charge ( $I_C=25\text{A}$ )

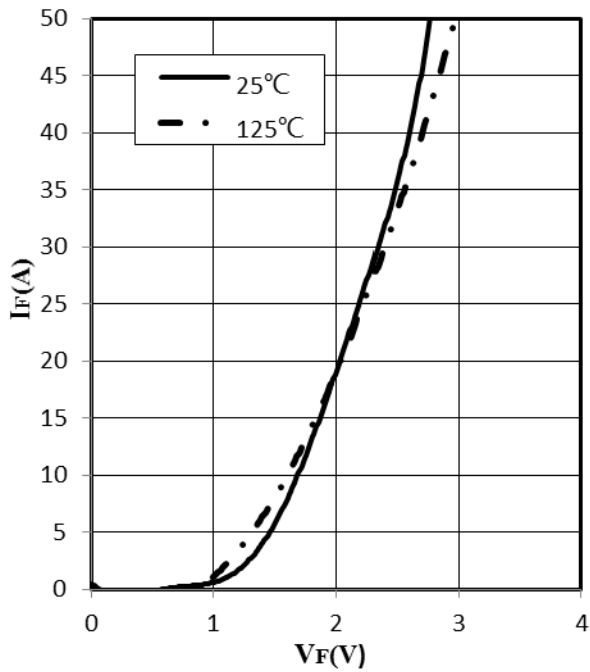


Fig 17. Typical diode forward current as a function of forward voltage

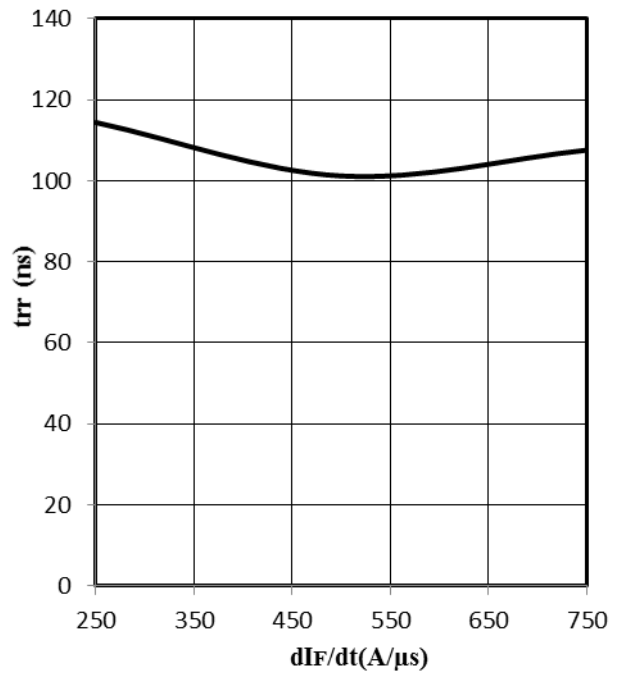


Fig 18. Typical  $t_{rr}$  as a function of  $dI_F/dt$

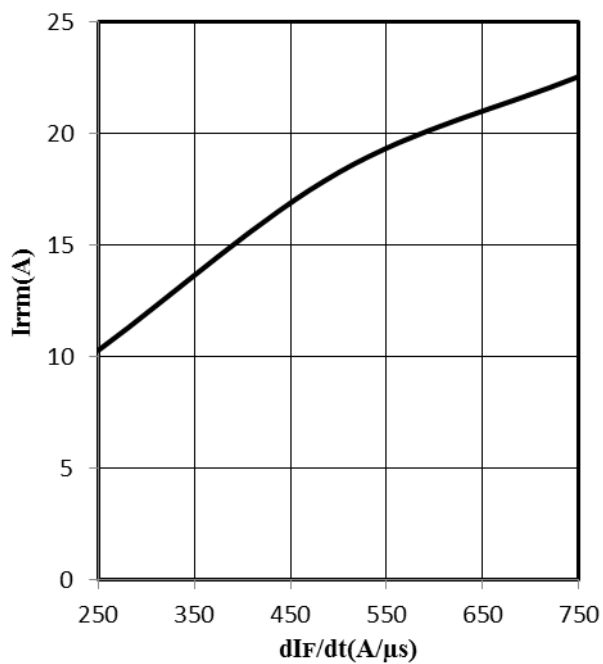


Fig 19. Typical  $I_{rrm}$  as a function of  $dI_F/dt$

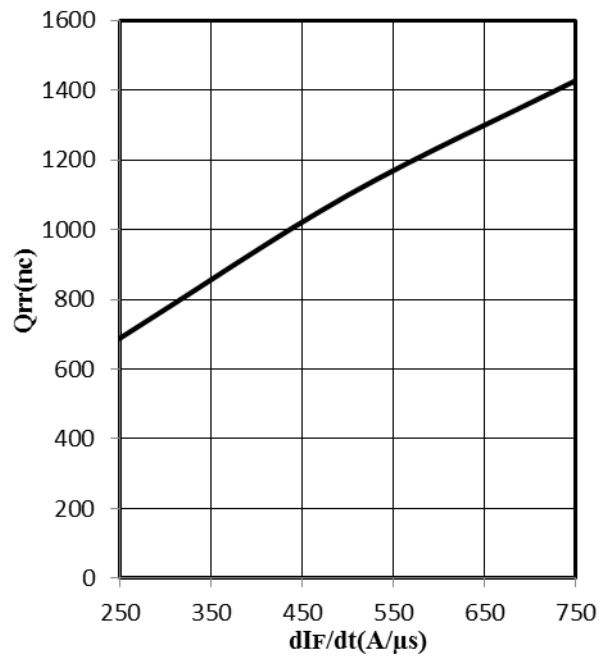


Fig 20. Typical  $Q_{rr}$  as a function of  $dI_F/dt$

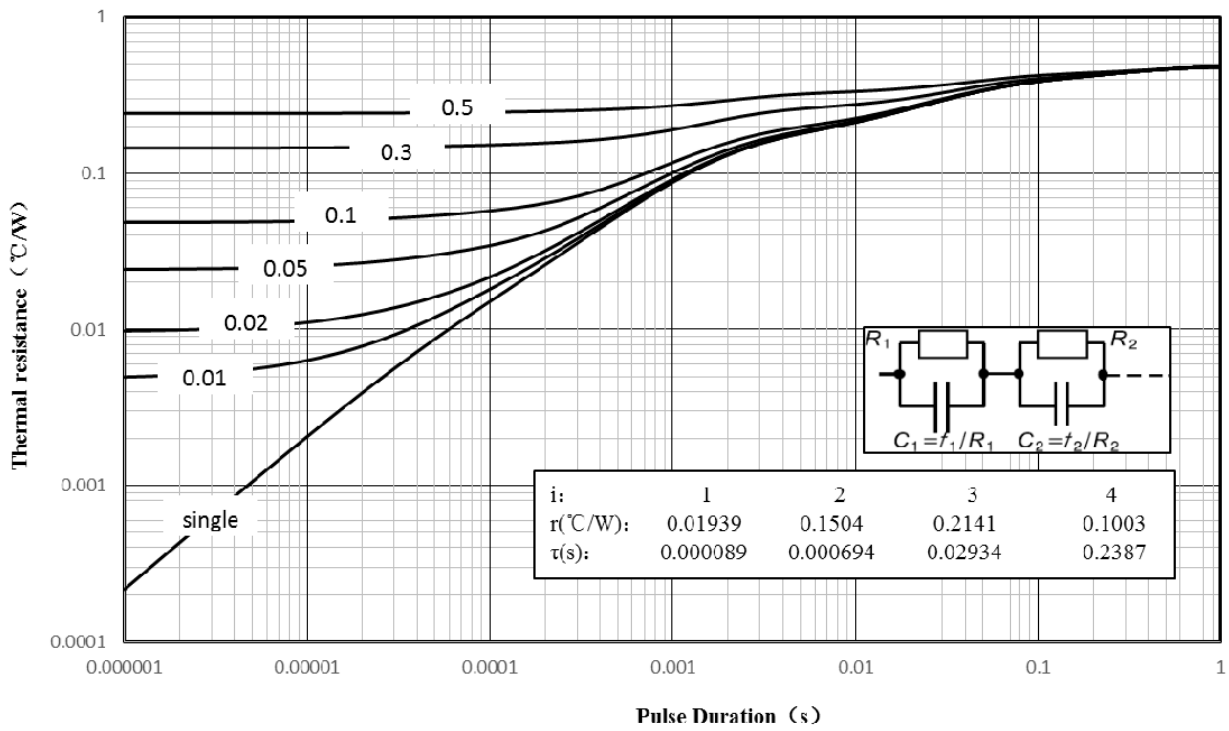


Fig 21. IGBT transient thermal resistance(D=tp/T)